

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
1	BRS	36	substrate with metal with plate with reinforce\$6 with resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:44				S2
2	BRS	3	substrate with metal with plate with reinforce\$6 with resin and bond\$ with chip with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/08 12:06				S3
3	BRS	13	substrate with metal with plate with resin and reinforce\$6 and bond\$ with chip with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 20:31				S4
4	BRS	5	substrate and second with metal with plate with reinforce\$6 and bond\$ with chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 20:34				S5

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
5	BRS	3	substrate and second with metal with plate with reinforce\$6 and bond\$ with chip and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 20:34				S6
6	BRS	24	second with metal with plate with reinforce\$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 20:36				S7
7	BRS	20	second with metal with plate with reinforce\$6 and semiconductor and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:16				S8
8	BRS	17	("3601753" "4028509" "4096577" "4197586" "4328399" "4456800" "4567354" "4611261").PN. OR ("4675787").URP N.	US-PGPUB; USPAT; USOCR	2005/03/19 21:10				S9

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Error	Ref #
9	BRS	36	("3710193" "4074342" "4296456" "4533976" "4677526" "4766520" "4802859" "4873615" "4916575" "4985747" "4989318" "5031069" "5045971" "5081764" "5157588").PN. OR ("5408383").URP N.	US-PGPUB; USPAT; USOCR	2005/03/19 21:13				S10
10	BRS	6	metal with plate with reinforc\$6 with pressure and semiconductor and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:20				S11
11	BRS	27	(metal or plate) with reinforc\$6 with pressure with resin and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:40				S12

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
12	BRS	4	upper with lower with reinforc\$6 with pressure with resin and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:42				S13
13	BRS	4	upper with lower with reinforc\$6 with pressure and resin with seal\$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:43				S14
14	BRS	49	upper with lower with plate with pressure and resin with seal\$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:44				S15
15	BRS	49	("3729573" "4377548" "4470786" "4626185" "4823234" "4954307").PN. OR ("5091341").URP N.	US-PGPUB; USPAT; USOCR	2005/03/19 22:11				S16

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
16	BRS	32	(("3729573" "4377548" "4470786" "4626185" "4823234" "4954307") .PN. OR ("5091341") .URP N.) and (pressure or force)	US-PGPUB; USPAT; USOCR	2005/03/19 22:11				S17
17	BRS	21	(("3729573" "4377548" "4470786" "4626185" "4823234" "4954307") .PN. OR ("5091341") .URP N.) and (pressure or force) and plate	US-PGPUB; USPAT; USOCR	2005/03/19 22:12				S18
18	BRS	12	substrate with metal with plate with reinforce\$6 and resin with (seal\$6 or encapsulat\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 22:26				S19

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
19	BRS	93	substrate and plate with reinforce\$6 and resin with (seal\$6 or encapsulat\$6) and (pressure or force) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 22:28				S21
20	BRS	9	substrate and metal with plate with reinforce\$6 and resin with (seal\$6 or encapsulat\$6) and (pressure or force) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 22:30				S22

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
21	BRS	6	substrate with metal with plate with (force or pressure) and resin with (seal\$6 or encapsulat\$6) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 12:24				S24
22	BRS	96	substrate with (metal or plate) with (force or pressure) and resin near (seal\$6 or encapsulat\$6) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 22:34				S25

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
23	BRS	96	substrate with (metal or plate) with (force or pressure) and resin near (seal\$6 or encapsulat\$6) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 23:04				S26
24	BRS	5	reinforc\$6 with (metal or plate) with (force or pressure) and resin near (seal\$6 or encapsulat\$6) with (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 23:05				S28

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
25	BRS	50	("4447716" "4649418" "4682017" "4725924" "4731645" "4731700").PN. OR ("4962415").URP N.	US-PGPUB; USPAT; USOCR	2005/03/19 23:14				S29
26	BRS	18	(substrate or plate) with reinforce\$6 with resin with (seal\$6 or encapsulat\$6) with (pressure or force)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 12:13				S30
27	BRS	75	(substrate or plate) with reinforce\$6 same resin same (seal\$6 or encapsulat\$6) same (pressure or force)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 15:51				S31

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
28	BRS	66	(438/124).ccls. and resin with (seal\$6 or encapsulat\$6) and reinforc\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 12:41				S32
29	BRS	8	"5200601"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 15:17				S33
30	BRS	6	("3622419" "4849803" "4994659" "5200601" "5898215").PN. OR ("6069402").URP N.	US-PGPUB; USPAT; USOCR	2005/03/25 15:46				S34
31	BRS	26	(substrate or plate) with reinforce\$6 same resin same (seal\$6 or encapsulat\$6) same (compress\$6 or thermocompress\$ 6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:11				S35

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
32	BRS	15	resin with (seal\$6 or encapsulat\$6) same (compress\$6 or thermocompress\$ 6) with reinforc\$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:18				S36
33	BRS	71	resin with (seal\$6 or encapsulat\$6) same (compress\$6 or thermocompress\$ 6 or press\$6 or force) with reinforc\$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:19				S37

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
34	BRS	44	substrate with (metal or plate) with reinforce\$6 with resin and (saw\$6 or dic\$6 or singulat\$6 or separat\$6) and reinforc\$6 with (pressur\$6 or compress\$6 or thermocompress\$ 6 or forc\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:57				S38
35	BRS	91	(saw\$6 or dic\$6 or singulat\$6 or separat\$6) with (wafer or substrate) and (compress\$6 or thermocompress\$ 6) with resin with seal\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:59				S39

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
36	BRS	40	(saw\$6 or dic\$6 or singulat\$6 or separat\$6) with (wafer or substrate) and (compress\$6 or thermocompress\$6) with resin with seal\$6 and (support\$ or reinforc\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 17:00				S40

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	1	card with roll near film with coat\$4 same heat\$6 and (divid\$4 or saw\$5 or dic\$4 or singulat\$4 or separat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:52			
2	BRS	L4	5	card with film with coat\$4 with heat\$6 and (divid\$4 or saw\$5 or dic\$4 or singulat\$4 or separat\$5) and roll\$4 near film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:49			
3	BRS	L5	1	card with roll\$5 near film with coat\$4 same heat\$6 and (divid\$4 or saw\$5 or dic\$4 or singulat\$4 or separat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:53			
4	BRS	L6	9	card with roll\$5 near film same heat\$6 and (divid\$4 or saw\$5 or dic\$4 or singulat\$4 or separat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:53			
5	BRS	L9	34	card with roll\$4 with film with heat\$6 and (divid\$4 or saw\$5 or dic\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 15:28			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
6	BRS	L12	23	card with roll\$4 with film with heat\$6 and (divid\$4 or saw\$5 or dic\$4 or singulat\$4 or separat\$5 or separat\$5) near card	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 15:45			